# USB Single Channel Transceiver

The NCN2500 Integrated Circuit is a single channel transceiver designed to accommodate the physical USB Port with a microcontroller digital I/O. The part is fully USB compliant and supports the full 12 Mbps speed. On the other hand, the NCN2500 device includes the pullup resistors as defined by the USB–ECN new specifications.

#### Features

- Compliant to the USB Specification, Version 2.0, Low and Full Speed
- Very Small Footprint Due to the QFN-16 Package
- Integrated D+/D- Pullup Resistors
- Operates Over the Full 1.5 V to 3.6 V Supply
- Pb–Free Package is Available\*

#### **Typical Applications**

- Portable Computer
- Cellular Phone



## **ON Semiconductor®**

http://onsemi.com



Y = Year

- W = Work Week
- = Pb–Free Package



Figure 1. Typical Application

#### **PIN CONNECTIONS**



#### ORDERING INFORMATION

Device	Package	Shipping†	
NCN2500MNR2	QFN-16	3000 Tape & Reel	
NCN2500MNR2G	QFN–16 (Pb–Free)	3000 Tape & Reel	

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



Figure 2. Block Diagram

### PIN FUNCTION DESCRIPTION

Pin	Symbol	Function	Description
1	DSPD	INPUT	The DSPD logic level (Data Speed) activates the Low or the High speed operation on the USB port. DSPD = Low Low Speed, RPU1 and RPU2 connected to D– DSPD = High Full Speed, RPU1 and RPU2 connected to D+
2	RCV	OUTPUT	This pin interfaces the USB signals with the microcontroller digital line. The data present on the $D+/D-$ pins are translated onto this signal.
3	Vp	I/O	$ \begin{array}{l} \mbox{This pin, associated with Vm, is an I/O system interface signal depending upon the \overline{OE} logic state: \overline{OE} = Low Vp is a Plus driver Input (from \mu C to USB bus) \overline{OE} = High Vp is a Plus receiver Output (from USB bus to \mu C)$
4	Vm	I/O	$ \begin{array}{ll} \mbox{This pin, associated with Vp, is an I/O system interface signal depending upon the} \\ \hline \overline{OE} \mbox{ logic state:} \\ \hline \overline{OE} \mbox{ = Low } & \mbox{Vm is a Minus driver Input (from $\mu$C to USB bus)} \\ \hline \overline{OE} \mbox{ = High } & \mbox{Vm is a Minus receiver Output (from USB bus to $\mu$C)} \\ \end{array} $
5	EN_VObus	INPUT	Digital input to control the VObus voltage.      EN_VObus = Low    VObus connected to Vreg      EN_VObus = High    VObus disconnected from Vreg (Hi Z)
6	GND	PWR	This pin carries the digital and USB ground level. High Quality PCB design shall be observed to avoid uncontrolled voltage spikes.
7	SPND	INPUT	The SPND digital signal (SUSPEND) selects the operation mode to reduce the power supply current.      SPND = Low    Normal operation      SPND = High    Suspend mode, no activity takes place
8	NC	_	No Connection, shall be neither grounded, nor connected to Vcc or Vbus.
9	ŌE	INPUT	This pin activates the operating mode of the D-/D+ signals. $\overline{OE}$ = Low logic levelData are transmitted onto the USB bus $\overline{OE}$ = High logic levelData are received from the USB bus
10	D-	I/O	This pin is connected to the USB Minus Data line I/O. The data direction depends upon the $\overline{\text{OE}}$ logic state.
11	D+	I/O	This pin is connected to the USB Plus Data line I/O The data direction depends upon the $\overline{\text{OE}}$ logic state.
12	Vreg	PWR	This pin provides a 3.3 V regulated voltage to supply the internal USB blocks and the external termination bias resistor. An external circuit can be connected to this LDO, assuming the current does not extend the maximum rating (50 mA).
13	VObus	OUTPUT, PWR	This pin connects the Vreg voltage to the 1.5 k external pullup resistor. The VObus voltage is controlled by the logic states present Pin 5. The R <sub>DSon</sub> of the internal PMOS device (reference S5 in the Block Diagram) is 10 $\Omega$ typical.
14	Vusb	PWR	This pin is connected to the USB port +Vcc supply voltage.
15	Vcc	PWR	This pin provides the interface power supply. The power source can be an external supply or can be derived from the USB + Vusb voltage.
16	EN_RPU	INPUT	This pin activates or deactivate the internal RPU1 and RPU2 pullup resistors:      EN_RPU = H    RPU1 and RPU2 activated      EN_RPU = L    RPU1 and RPU2 deactivated

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Power Supply Voltage	Vcc	6.0	V
Digital Input Pins	Vind	-0.5 V < Vin < Vcc + 0.5 V, but < 6.0 V	V
Digital Input Pins	Vid	-0.5 V < Vin < AGND + 0.5 V, but < 6.0 V	V
Digital Input Pins	Ibias	–35 mA < Ibias < 35 mA	mA
ESD Capability, HBM (Note 1) Vusb, D+, D–, GND Any Other Pins Machine Model, Any Pins	V <sub>ESD</sub>	10 2.0 200	k∨ k∨ ≻
QFN–16 Package Power Dissipation @ Tamb = +85°C Thermal Resistance, Junction–to–Air (R <sub>θJA</sub> )	P <sub>DS</sub> R <sub>θJA</sub>	470 85	mW ∘C/W
Operating Ambient Temperature Range	T <sub>A</sub>	-40 to +85	°C
Operating Junction Temperature Range	TJ	-40 to +125	°C
Maximum Junction Temperature (Note 2)	T <sub>Jmax</sub>	+150	°C
Storage Temperature Range	T <sub>sg</sub>	-65 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected. 1. Human Body Model,  $R = 1500 \Omega$ , C = 100 pF; Machine Model.

2. Absolute Maximum Rating beyond which damage(s) to the device may occur.

### **ELECTRICAL CHARACTERISTICS**

Input EN\_RPU Pulldown Resistor @VCC = 3.3 V

Characteristic	Symbol	Pin	Min	Тур	Max	Unit	
<b>DIGITAL PARAMETERS SECTION</b> @ <b>1.5 V &lt; Vcc &lt; 3.6 V</b> (-40°C to +85°C ambient temperature, unless otherwise noted.) NOTE: Digital inputs undershoot < -0.3 V to ground, digital inputs overshoot < 0.3 V to Vcc.							
High Level Input Voltage DSPD, Vp, Vm, EN_VObus, SPND, OE, EN_RPU	V <sub>IH</sub>	1, 3, 4, 5, 7, 9, 16	0.80*Vcc	-	-	V	
Low Level Input Voltage DSPD, Vp, Vm, <u>EN_VObus</u> , SPND, <u>OE</u> , EN_RPU	V <sub>IL</sub>	1, 3, 4, 5, 7, 9, 16	-	-	0.20*Vcc	V	
High Level Output Voltage RCV, Vp, Vm @ I <sub>OH</sub> = 1.0 mA	V <sub>OH</sub>	2, 3, 4	0.80*Vcc	-	-	V	
Low Level Output Voltage RCV, Vp, Vm @ I <sub>OL</sub> = 1.0 mA	V <sub>OL</sub>	2, 3, 4	-	-	0.20*Vcc	V	
Input Leakage Current DSPD, Vp, Vm, EN_VObus, SPND, OE, EN_RPU	Ι <sub>ΙL</sub>	1, 3, 4, 5, 7, 9, 16	_	-	±5.0	μA	

RPU

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300

kΩ

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TRANSCEIVER SECTION @ 1.5 V < Vcc < 3.6 V (-40°C to +85°C ambient temperature, unless otherwise noted.)

Static Output High, D–, D+ @ $\overline{\text{OE}}$ = Low, R <sub>L</sub> = 15 k $\Omega$ to GND	V <sub>OH</sub>	10, 11	2.8	-	3.6	v
Static Output Low, D–, D+ @ $\overline{OE}$ = Low, R <sub>L</sub> = 1.5 k $\Omega$ to Vreg	V <sub>OL</sub>	10, 11	-	-	0.3	V
Single Input Receiver Threshold	V <sub>SE</sub>	10, 11	0.8	-	2.0	V
Single Ended Receiver Hysteresis (Note 3)	-	-	-	200	-	mV
Differential Input Sensitivity $  D+ - D-   @ 0.8 V < V_{CM} < 2.5 V$ (Note 3)	V <sub>DI</sub>	10, 11	0.2	-	-	V
Differential Common Mode Including the $V_{DI}$	V <sub>CM</sub>	10, 11	0.8	-	2.5	V
Differential Receiver Hysteresis (Note 3)	-	10, 11	-	70	-	mV
D+ and D– Transceiver Hi–Z State Leakage Current @ $\overline{OE}$ = 1, 0 V < Vusb < 3.3 V	ILO	10, 11	-	-	±10	μΑ
Transceiver Input Capacitance (Note 3)	Cin	10, 11	-	-	20	pF
Transceiver Output Resistance (Note 3)	Z <sub>DRV</sub>	10, 11	28	-	44	Ω
Transceiver Input Impedance (Note 3)	Z <sub>IN</sub>	10, 11	10	-	-	MΩ
Internal RPU1 Pull Resistor	R <sub>RPU-1</sub>	10, 12	900	-	1575	Ω
Internal RPU2 Pull Up Resistor	R <sub>RPU-2</sub>	10, 12	525	-	1515	Ω
LOW SPEED DRIVER OPERATION (Note 3)						
Transition Rise Time @ $C_L = 50 \text{ pF}$ @ $C_L = 600 \text{ pF}$	tr	10, 11	75 75		300 300	ns
Transition Fall Time @ $C_L = 50 \text{ pF}$ @ $C_L = 600 \text{ pF}$	tf	10, 11	75 75		300 300	ns
Rise and Fall Time Matching	tr, tf	10, 11	80	-	125	%
Output Signal Crossover Voltage	V <sub>CRS</sub>	10, 11	1.3	-	2.0	V
Data Transaction Rate	Drate	10, 11	-	-	1.5	Mbs

3. Parameter guaranteed by design, not production tested.

#### ELECTRICAL CHARACTERISTICS (continued)

Characteristic	Symbol	Pin	Min	Тур	Max	Unit
FULL SPEED DRIVER OPERATION (Note 4)						
Transition Rise Time @ $C_L = 50 \text{ pF}$	tr	10, 11	4.0	-	20	ns
Transition Fall Time @ $C_L = 50 \text{ pF}$	tf	10, 11	4.0	-	20	ns
Rise and Fall Time Matching	tr, tf	10, 11	90	-	110	%
Output Signal Crossover Voltage	V <sub>CRS</sub>	10, 11	1.3	-	2.0	V
Data Transaction Rate	Drate	10, 11	-	-	12	Mbs
TRANSCEIVER TIMING (Note 4)						
OE to RCVR Hi–Z Delay (see Figure 3)	t <sub>PVZ</sub>	9	-	-	15	ns
Receiver Hi–Z to Transmit Delay (see Figure 3)	t <sub>PZD</sub>	-	15	-	-	ns
OE to DRVR Hi–Z Delay (see Figure 3)	t <sub>PDZ</sub>	-	-	-	15	ns
Driver Hi–Z to Receiver Delay (see Figure 3)	t <sub>PZV</sub>	-	15	-	-	ns
Vp/Vm to D+/D- Propagation Delay (see Figure 6)	t <sub>PLH</sub>	3, 4, 10, 11	_	-	15	ns
Vp/Vm to D+/D- Propagation Delay (see Figure 6)	t <sub>PHL</sub>	3, 4, 10, 11	_	-	15	ns
D+/D- to RCV Propagation Delay @ $1.5 < Vcc < 5.5 V$ (see Figure 5) C <sub>L</sub> = 25 pF tr = tf = $3.0 \text{ ns}$	t <sub>PLH</sub>	11, 10, 2	-	-	15	ns
D+/D- to RCV Propagation Delay @ $1.5 < Vcc < 5.5 V$ (see Figure 5) C <sub>L</sub> = 25 pF tr = tf = $3.0 \text{ ns}$	t <sub>PHL</sub>	11, 10, 2	-	-	15	ns
D+/D– to Vp/D– Propagation Delay @ $1.5 < Vcc < 5.5 V$ (see Figure 5) C <sub>L</sub> = 25 pF tr = tf = $3.0 \text{ ns}$	t <sub>PLH</sub>	11, 10, 3	-	-	8.0	ns
D+/D- to Vm/D- Propagation Delay @ $1.5 < Vcc < 5.5 V$ (see Figure 5) C <sub>L</sub> = 25 pF tr = tf = 3.0 ns	t <sub>PHL</sub>	11, 10, 4	-	-	8.0	ns
POWER SUPPLY SECTION @ 1.5 V < Vcc < 3.6 V (-40°C	to +85°C amb	pient temperatu	ure, unless othe	erwise noted.	)	
Digital Supply Voltage	Vcc	15	1.5	-	3.6	V
USB Port Input Supply Voltage	Vusb	14	4.0	-	5.25	V
Output Regulated Voltage @ 4.0 V < Vusb < 5.25 V, Cin = 4.7 $\mu$ F, Cout = 1.0 $\mu$ F, Ireg = 100 mA	Vreg	12	3.0	3.3	3.6	V
Output Switched Voltage @ Io = 1.0 mA, Cin = $4.7 \mu\text{F}$	Vobus	13	3.0	3.3	3.6	V
Line Regulation Output Voltage	Vreg	12	-	0.1	-	%
Standby Current @ Vusb = 5.25 V, $\overline{OE}$ = H, SPND = H, D+ and D- are Idle, Vcc = 3.6 V	I <sub>VCC</sub>	14	-	1.0	-	μΑ
Standby Current @ Vusb = 5.25 V, $\overline{OE}$ = H, SPND = L, D+ and D- are Idle, Vcc = 3.6 V	IVCC	14	-	1.0	-	μΑ
Operating Current $\overline{OE}$ = L, D– and D+ Active, SPND = L (Note 4), Transmitter Mode @ F = 6.0 MHz, C <sub>L</sub> = 50 pF @ F = 750 kHz, C <sub>L</sub> = 600 pF	Ivcc	14	_	300 40		μA
Operating Current $\overline{OE}$ = H, D– and D+ Active, SPND = L (Note 4), Receiver Mode @ F = 6.0 MHz, C <sub>L</sub> = 25 pF @ F = 750 kHz, C <sub>L</sub> = 25 pF	lvcc	14	_	1.5 250	-	mA μA

4. Parameter guaranteed by design, not production tested.

## ELECTRICAL CHARACTERISTICS (continued)

Characteristic	Symbol	Pin	Min	Тур	Мах	Unit			
POWER SUPPLY SECTION @ 1.5 V < Vcc < 3.6 V (continued) (-40°C to +85°C ambient temperature, unless otherwise noted.)									
USB Supply Current @ D- and D+ are Idle, Vusb = $5.25$ V and: @ SPND = 1, $\overline{OE}$ = 1, DSPD = 0, EN_RPU = 0 @ SPND = 0, $\overline{OE}$ = 1, DSPD = 1, EN_RPU = 0 @ SPND = 0, $\overline{OE}$ = 0, DSPD = 0, EN_RPU = 0 @ SPND = 1, $\overline{OE}$ = 1, DSPD = 0, EN_RPU = 1	I <sub>BUS</sub>	14		120 1.7 1.7 320	200 - - 500	μA mA mA μA			
@ D- and D+ are Active, $C_L = 50 \text{ pF}$ , Vusb = 5.25 V, SPND = 0, $\overline{OE} = 0$ , DSPD = 1, F = 6.0 MHz (Note 5) @ EN_RPU = Low @ EN_RPU = High @ D- and D+ are Active (Note 5) Vusb = 5.25 V, SPND = 0, $\overline{OE} = 0$ , DSPD = 1, F = 750 kHz, $C_L = 600 \text{ pF}$ F = 750 kHz, $C_L = 300 \text{ pF}$				8.3 9.4 5.4 3.9		mA mA mA			

5. Parameter guaranteed by design, not production tested.

EN_RPU	DSPD	S1	S2	S3	Data Line	USB	Note
0	Х	Х	Х	Х	x	×	Internal RPU Deactivated, S1 and S3 are Forced OPEN
1	1	Open	Х	Open	Vbus Off	Х	Internal RPU disabled
1	1	Close	Close	Open	Idle	Full Speed	Internal RPU Activated
1	1	Closed	Open	Open	Receiving	Full Speed	Internal RPU Activated
1	0	Open	Х	Open	Vbus Off	Х	Internal RPU disabled
1	0	Open	Close	Close	Idle	Low Speed	Internal RPU Activated
1	0	Open	Open	Close	Receiving	Low Speed	Internal RPU Activated

#### Table 1. Internal RPU1 and RPU2 Pullup Resistors Control

6. See Figure 8 and Figure 9.

## Table 2. Transmit Mode Interface Control ( $\overline{OE} = 0 \rightarrow$ Transmit Mode)

SPND	Vp	Vm	D+	D-	RCV	STATE
0	0	0	0	0	Х	SE0
0	0	1	0	1	0	Low
0	1	0	1	0	1	High
0	1	1	1	1	Х	Undefined
1	0	0	0	0	0	Suspend
1	0	1	0	1	0	Suspend
1	1	0	1	0	0	Suspend
1	1	1	1	1	0	Suspend

## Table 3. Receive Mode Interface Control ( $\overline{OE} = 1 \rightarrow \text{Receive Mode}$ )

SPND	D+	D-	Vp	Vm	RCV	STATE
0	0	0	0	0	Х	SE0
0	0	1	0	1	0	Low
0	1	0	1	0	1	High
0	1	1	1	1	Х	Undefined
1	0	0	0	0	0	Suspend
1	0	1	0	1	0	Suspend
1	1	0	1	0	0	Suspend
1	1	1	1	1	0	Suspend



Figure 3. Enable and Disable USB Times



Figure 4. USB Line Rise and Fall Times



Figure 5. Receiver Propagation Delays



Figure 6. Driver Propagation Delays







Figure 8. Internal RPU1 and RPU2 Pullup Resistors Operation, IDLE Mode



NOTE: Internal Pullup Resistor Range: RPU1: 900  $\Omega$  min–1575  $\Omega$  max, RPU2: 525  $\Omega$  min–1515  $\Omega$  max

#### Figure 9. Internal RPU1 and RPU2 Pullup Resistors Activated, RECEIVING Mode

#### **TYPICAL APPLICATIONS**



In this application, the two internal pullup resistors (RPU1 and RPU2) are used to bias the USB line. Consequently, the VObus voltage is deactivated (Pin 5 connected to Vcc).





Figure 11. Peripheral are Powered by the Vreg Supply

## **TYPICAL APPLICATIONS**



Note: Pin 16 can be left open, due to the internal pull-down resistor, or connected to ground.

Figure 12. Using External Pullup Resistors

#### PACKAGE DIMENSIONS

QFN-16 **MNR SUFFIX** CASE 485G-01 ISSUE B



- NOTES:
  DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  CONTROLLING DIMENSION: MILLIMETERS.
  DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
  COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
  Lmax CONDITION CAN NOT VIOLATE 0.2 MM MINIMUM SPACING BETWEEN LEAD TIP AND FLAG

	MILLIN	IETERS			
DIM	MIN	MAX			
Α	0.80	1.00			
A1	0.00	0.05			
A3	0.20 REF				
b	0.18	0.30			
D	3.00	BSC			
D2	1.65	1.85			
Е	3.00	BSC			
E2	1.65	1.85			
е	0.50 BSC				
ĸ	0.20				
L	0.30	0.50			

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